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## FDC6303N Digital FET, Dual N-Channel

## **General Description**

These dual N-Channel logic level enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. This device has been designed especially for low voltage applications as a replacement for digital transistors in load switching applications. Since bias resistors are not required this one N-Channel FET can replace several digital transistors with different bias resistors like the IMHxA series.

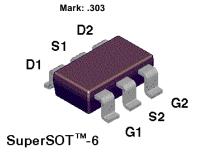
#### **Features**

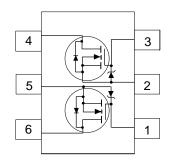
■ 25 V, 0.68 A continuous, 2 A Peak.

$$\begin{split} R_{\text{DS(ON)}} &= 0.6 \; \Omega \; @ \; \text{V}_{\text{GS}} = 2.7 \; \text{V} \\ R_{\text{DS(ON)}} &= 0.45 \; \Omega \; @ \; \text{V}_{\text{GS}} = 4.5 \; \text{V}. \end{split}$$

- Very low level gate drive requirements allowing direct operation in 3V circuits. V<sub>GS(th)</sub> < 1.5 V.</li>
- Gate-Source Zener for ESD ruggedness. >6kV Human Body Model
- Replace multiple NPN digital transistors (IMHxA series) with one DMOS FET.







**Absolute Maximum Ratings**  $T_A = 25$ °C unless otherwise noted

Symbol	Parameter		FDC6303N	Units
V <sub>DSS</sub>	Drain-Source Voltage		25	V
$V_{GSS}$	Gate-Source Voltage		8	V
D	Drain Current - Continuous		0.68	А
	- Pulsed		2	
<b>)</b>	Maximum Power Dissipation	(Note 1a)	0.9	W
		(Note 1b)	0.7	
$T_J$ , $T_{STG}$	Operating and Storage Temperature Range		-55 to 150	°C
SD	Electrostatic Discharge Rating MIL-STD-883D Human Body Model (100pf / 1500 Ohm)		6.0	kV
HERMA	L CHARACTERISTICS	<u>.</u>		<u>.</u>
R <sub>OJA</sub>	Thermal Resistance, Junction-to-Ambie	nt (Note 1a)	140	°C/W
R <sub>euc</sub>	Thermal Resistance, Junction-to-Case	(Note 1)	60	°C/W

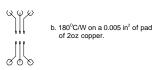
Symbol	Parameter	Conditions	Min	Тур	Max	Units
OFF CHAP	RACTERISTICS		•			•
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	25			V
$\Delta$ BV <sub>DSS</sub> / $\Delta$ T <sub>J</sub>	Breakdown Voltage Temp. Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25 °C		26		mV /°C
DSS	Zero Gate Voltage Drain Current	$V_{DS} = 20 \text{ V}, \ V_{GS} = 0 \text{ V}$			1	μA
		T <sub>J</sub> = 55°C			10	μA
GSS	Gate - Body Leakage Current	$V_{GS} = 8 \text{ V}, \ V_{DS} = 0 \text{ V}$			100	nA
ON CHARA	ACTERISTICS (Note 2)		•			•
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold Voltage Temp.Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25 °C		-2.6		mV /°C
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	0.65	0.8	1.5	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 4.5 \text{ V}, I_{D} = 0.5 \text{ A}$		0.33	0.45	Ω
		T <sub>J</sub> =125°C		0.52	0.8	
		$V_{GS} = 2.7 \text{ V}, \ I_{D} = 0.2 \text{ A}$		0.44	0.6	1
D(ON)	On-State Drain Current	$V_{GS} = 2.7 \text{ V}, \ V_{DS} = 5 \text{ V}$	0.5			Α
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 0.5 \text{ A}$		1.45		S
DYNAMIC (	CHARACTERISTICS					
$C_{iss}$	Input Capacitance	$V_{DS} = 10 \text{ V}, \ V_{GS} = 0 \text{ V}, $ f = 1.0 MHz		50		pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		28		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			9		pF
SWITCHIN	G CHARACTERISTICS (Note 2)					_
D(on)	Turn - On Delay Time	$V_{DD} = 6 \text{ V}, I_{D} = 0.5 \text{ A},$		3	6	ns
r	Turn - On Rise Time	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 50 \Omega$		8.5	18	ns
t <sub>D(off)</sub>	Turn - Off Delay Time			17	30	ns
t <sub>r</sub>	Turn - Off Fall Time			13	25	ns
$Q_g$	Total Gate Charge	$V_{DS} = 5 \text{ V}, I_{D} = 0.5 \text{ A},$		1.64	2.3	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 4.5 V		0.38		nC
$Q_{gd}$	Gate-Drain Charge			0.45		nC
DRAIN-SO	URCE DIODE CHARACTERISTICS AND MAX	XIMUM RATINGS	1	1		
l <sub>s</sub>	Maximum Continuous Source Current				0.3	Α
$V_{SD}$	Drain-Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_{S} = 0.5 \text{ A (Note 2)}$			0.83	1.2	V

Notes:

1. R<sub>BJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>BJC</sub> is guaranteed by design while  $R_{\theta^{CA}}$  is determined by the user's board design.  $R_{\theta^{JA}}$  shown below for single device operation on FR-4 in still air.



a. 140°C/W on a 0.125 in² pad of 2oz copper.



2. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2.0%.

## **Typical Electrical Characteristics**

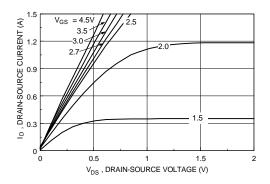


Figure 1. On-Region Characteristics.

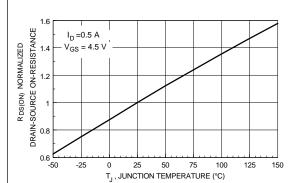


Figure 3. On-Resistance Variation with Temperature.

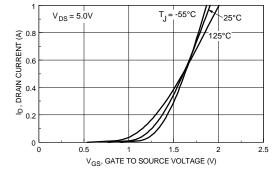


Figure 5. Transfer Characteristics.

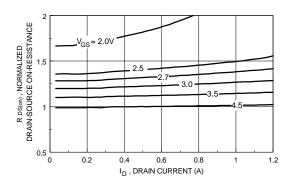


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

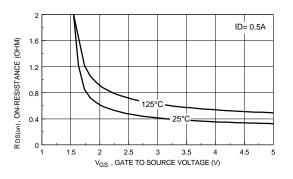


Figure 4. On Resistance Variation with Gate-To- Source Voltage.

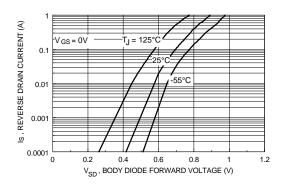


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

## **Typical Electrical And Thermal Characteristics**

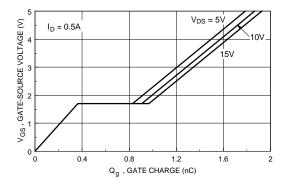


Figure 7. Gate Charge Characteristics.

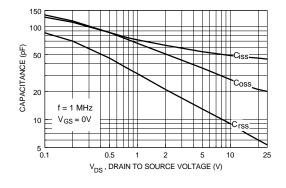


Figure 8. Capacitance Characteristics.

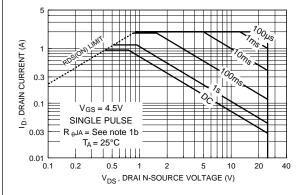


Figure 9. Maximum Safe Operating Area.

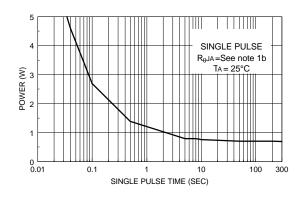


Figure 10. Single Pulse Maximum Power Dissipation.

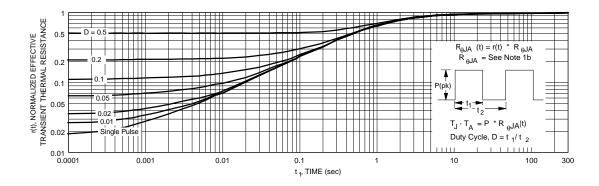


Figure 11. Transient Thermal Response Curve.

Note: Thermal characterization performed using the conditions described in note 1b.Transient thermal response will change depending on the circuit board design.

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